Intelligent Compaction Sub-Task Group
Meeting Minutes and Action Items
October 8, 2013
10:00 AM to 2:00 PM
Location: Geotechnical Conference Room
5900 Folsom Blvd.
Sacramento, CA 95819

Outline of Discussion

Agenda Review:
The meeting began at 10:00 AM with self introductions.
Background/Purpose of meeting/group by Chuck

a. Develop IC specs
b. Pilot projects

Add to agenda – Availability of fed funding for pilot projects

Review Action Items:

a. Draft Specifications were sent out by Ebi.
b. Spreadsheet showing manufacturers responses to question will be due next meeting.
c. EDC FHWA Funding will be discussed later in this meeting.

Review RPC Workplan Status:
None.

IC Equipment Manufacturers
This meeting was an opportunity for IC equipment manufacturers to give a short presentation and answer questions from sub task group about IC equipment. A questionnaire (see handout) was sent in advance to the equipment manufacturers with questions that they needed to answer in their presentations or that they could respond to at the sub task group meeting.

IC Equipment Manufacturers Presentations on October 18, 2013:

1. Dynapac
2. Sakai
3. Trimble

Dynapac Presentation

- Dynapac will tack-on information with Trimble presentation

Trimble Presentation

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Outline of Discussion Continued

Trimble Presentation

1. System is brand independent
   a. Pass count
   b. Temperature sensors
   c. Compaction sensors
      i. Need to be calibrated/test strip
2. Data can be dump/process using Vision link
3. CT requires all IC data to be transferable to Veda
4. CT to asked for copies of answers to questions from previous equipment manufacturers' presentation
5. IC can pre-rolled to identify soft-spots
6. Monitor multi-lift capability
7. Escalon capable within Trimble systems (but not between different system ie: Trimble and Bomag)
8. For HMA with thin lifts vibrator is off. Therefore no compaction data or density-compaction sensors relations
9. Trimble can be transfer from equipment to equipment
10. Complete package full system cost between 25-30k
11. Lead time is from 1 day to 30 day
12. Spec language need GPS calibration/verification validating accuracy within ½ feet
13. Trimble to provide DOTs, projects, equipment that have used Trimble
14. CT requires all IC data to be transferable to Veda
    a. Pass count
    b. Temperature sensors
    c. Compaction sensors

Sakai Presentation (Powerpoint Presentation)

- Participated in CT IC effort about 2 years ago
- 15 minutes to assemble/disassemble CIS system on equipment
- Not echelon capable

<u>Every Day Counts Funding</u>

Steve Healow is looking into any available funding for implementing IC in California. There may be two pots of fed money for IC projects and more information should be available shortly.

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Outline of Discussion Continued

HMA IC Specs (Version 2)

a. Comment from Surveys have been incorporated
b. File format is CAiCE or Civil3D
c. Para 5: change ~~most~~ to must
d. Para 7: Deleted
e. Para 8: Fed will tried to find out what available for JIT
f. Para 8: Industry to provide suggestions
g. CT will look into roller speed issue in algorithm/data collected?
h. Para 12: Change to Item 13; from 0.6 mm to 0.0236 inches
i. Para 13: Check with equipment manufacturer on data mesh is appropriate
j. Para 15: change ~~7 days~~ to 5 days
k. Para 15: change ~~roller manufacturer~~ to roller manufacturer and IC system
l. Para 17: Manufacturer and Transtec (George) for review and provide feedback
m. Para 20: Delete
n. Add Para for Test Section when required
o. Para 21: change ~~daily~~ to twice daily
p. Para 21: Add section for QC technician to download, review, and provide a report out of Veda.
q. Para 24. Delete Item 7
r. Add requirement to validate temperature sensor measurement
s. Para 24: delete ~~stiffness response values~~
t. Para 25: Survey will convert 1.6 inch to 0.13333 feet
u. Para 26: Map will go somewhere else. Specs don't allow figure or graph.
v. Para 28: Take "daily" out

Reclamation IC Specs (Version 2)

Caltrans will revise to be consistent with HMA specification.

Schedule Next Meeting:

Next meeting: Nov 5, 2013 from 2-4pm. Go to meeting will be available.

Review Action Items:

See attached action items.

Meeting adjourned at **2:00** PM.

Intelligent Compaction Sub-Task Group
Meeting Minutes and Action Items
September 18, 2013
10:00 AM to 3:00 PM

Location: TransLab 5900 Folsom Blvd., Sacramento, CA

Action Items Summary

#	MEETING	ITEM	ACTION REQUIRED	WHO	DUE	STATUS
1.	10-8-13	IC Equipment manufacturers responses to questionnair	Spreadsheet summarizing IC equipment manufactures responses to questions	Rita Leahy	11-05-13	
2.	10-8-13	Specifications	Caltrans to revise specifications and send to STG prior to next meeting.	Ebi Fini	10-25-13	
3.	10-8-13	JITT Training	Determine if there is any JITT prepared and available for IC?	Steve Healow	11-05-13	
4.	10-8-13	Monitor Roller Speed	Check with TransTech about collecting roller speeds and including in daily reports.	Ebi Fini	11-05-13	
5.	10-8-13	Roller GPS Check	Need to verify procedures for checking GPS calibration.	Ebi Fini	11-05-13	